

PEELING OF INSULATING FILM FROM FFC

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Abstract of JP2002027626

PROBLEM TO BE SOLVED: To peel off conductors of an FFC maintaining satisfactory surface conditions.

SOLUTION: A laser beam L is applied to a resin film 11a of the end part of an FFC 10, under which conductors 12 of the FFC 10 exist by a CO2 laser emission device, and the resin film 11a is melted by the heat of the laser beam L to expose the conductors 12. The intensity of the laser beam L must be adjusted, so as not to damage the conductors 12 but to melt selectively the resin film 11a. The CO2 laser L has a lower basic emission intensity than a YAG laser and is easy to adjust the intensity. If the emission intensity of the CO2 laser L is increased to sublime the resin film 11a and the resin film 11a is removed by the sublimation simultaneously, when the conductors 12 are exposed, occurrence of remains of the resin film 11a is eliminated and a troublesome work can be saved.



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